

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5467099

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HELENA DEIRDRE O'SHEA	04/02/2019
LALAN JEE MISHRA	04/01/2019
AMIT GIL	03/28/2019
GARY CHANG	03/27/2019
MOHIT KISHORE PRASAD	04/05/2019
RICHARD DOMINIC WIETFELDT	04/01/2019
VINAY JAIN	04/03/2019
RECEIVING PARTY DATA	
Name:	QUALCOMM INCORPORATED
Street Address:	5775 MOREHOUSE DRIVE
City:	SAN DIEGO
State/Country:	CALIFORNIA
Postal Code:	92121-1714
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16219698
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Email:	qualcomm-pto@lozaip.com
Correspondent Name:	LOZA & LOZA LLP
Address Line 1:	305 NORTH SECOND AVENUE #127
Address Line 4:	UPLAND, CALIFORNIA 91786
ATTORNEY DOCKET NUMBER:	QCOM-3711US (181730)
NAME OF SUBMITTER:	JULIO LOZA
SIGNATURE:	/Julio Loza/
DATE SIGNED:	04/10/2019
Total Attachments: 18	

source=181730_Asst_2019-04-08_SIGNED#page1.tif
source=181730_Asst_2019-04-08_SIGNED#page2.tif
source=181730_Asst_2019-04-08_SIGNED#page3.tif
source=181730_Asst_2019-04-08_SIGNED#page4.tif
source=181730_Asst_2019-04-08_SIGNED#page5.tif
source=181730_Asst_2019-04-08_SIGNED#page6.tif
source=181730_Asst_2019-04-08_SIGNED#page7.tif
source=181730_Asst_2019-04-08_SIGNED#page8.tif
source=181730_Asst_2019-04-08_SIGNED#page9.tif
source=181730_Asst_2019-04-08_SIGNED#page10.tif
source=181730_Asst_2019-04-08_SIGNED#page11.tif
source=181730_Asst_2019-04-08_SIGNED#page12.tif
source=181730_Asst_2019-04-08_SIGNED#page13.tif
source=181730_Asst_2019-04-08_SIGNED#page14.tif
source=181730_Asst_2019-04-08_SIGNED#page15.tif
source=181730_Asst_2019-04-08_SIGNED#page16.tif
source=181730_Asst_2019-04-08_SIGNED#page17.tif
source=181730_Asst_2019-04-08_SIGNED#page18.tif

ASSIGNMENT

WHEREAS, WE,

1. **Helena Deirdre O'SHEA**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
2. **Lalan Jee MISHRA**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
3. **Amit GIL**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
4. **Gary CHANG**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
5. **Mohit Kishore PRASAD**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
6. **Richard Dominic WIETFELDT**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
7. **Vinay JAIN**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **EFFICIENT TECHNIQUE FOR COMMUNICATING BETWEEN DEVICES OVER A MULTI-DROP BUS** (collectively the “**INVENTIONS**”) for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter “**ASSIGNEE**”), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said **INVENTIONS**, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto **ASSIGNEE**, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said **INVENTIONS**, including all patent applications therefor that may have been filed or may be filed hereafter for said **INVENTIONS** in the United States, including but not limited to U.S. Application No. **16/219,698** filed **December 13, 2018**,

Qualcomm Reference No. **181730**, and all provisional applications relating thereto, together with Indian Application No. **201841003135**, filed **January 26, 2018**, Qualcomm Reference No. **181730IN1**, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

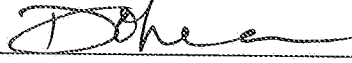
AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Cupertino, on April 2, 2019 
LOCATION DATE Helena Deirdre O'SHEA

Done at _____, on _____
LOCATION DATE Lalan Jee MISHRA

Done at _____, on _____
LOCATION DATE Amit GIL

Done at _____, on _____
LOCATION DATE Gary CHANG

Done at _____, on _____
LOCATION DATE Mohit Kishore PRASAD

Done at _____, on _____
LOCATION DATE Richard Dominic WIETFELDT

Done at _____, on _____
LOCATION DATE Vinay JAIN

ASSIGNMENT

WHEREAS, WE,

1. **Helena Deirdre O'SHEA**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
2. **Lalan Jee MISHRA**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
3. **Amit GIL**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
4. **Gary CHANG**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
5. **Mohit Kishore PRASAD**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
6. **Richard Dominic WIETFELDT**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
7. **Vinay JAIN**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **EFFICIENT TECHNIQUE FOR COMMUNICATING BETWEEN DEVICES OVER A MULTI-DROP BUS** (collectively the “**INVENTIONS**”) for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter “**ASSIGNEE**”), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said **INVENTIONS**, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto **ASSIGNEE**, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said **INVENTIONS**, including all patent applications therefor that may have been filed or may be filed hereafter for said **INVENTIONS** in the United States, including but not limited to U.S. Application No. **16/219,698** filed **December 13, 2018**,

Qualcomm Reference No. **181730**, and all provisional applications relating thereto, together with Indian Application No. **201841003135**, filed **January 26, 2018**, Qualcomm Reference No. **181730IN1**, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
LOCATION DATE
_____ Helena Deirdre O'SHEA

Done at San Diego, on 04/01/19
LOCATION DATE
_____ Lalan Jee MISHRA

Done at _____, on _____
LOCATION DATE
_____ Amit GIL

Done at _____, on _____
LOCATION DATE
_____ Gary CHANG

Done at _____, on _____
LOCATION DATE
_____ Mohit Kishore PRASAD

Done at San Diego ca, on 4/1/19
LOCATION DATE
_____ Richard Dominic WIETFELOTT
Richard Dominic WIETFELOTT

Done at _____, on _____
LOCATION DATE
_____ Vinay JAIN

ASSIGNMENT

WHEREAS, WE,

1. **Helena Deirdre O'SHEA**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
2. **Lalan Jee MISHRA**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
3. **Amit GIL**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
4. **Gary CHANG**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
5. **Mohit Kishore PRASAD**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
6. **Richard Dominic WIETFELDT**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
7. **Vinay JAIN**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **EFFICIENT TECHNIQUE FOR COMMUNICATING BETWEEN DEVICES OVER A MULTI-DROP BUS** (collectively the “**INVENTIONS**”) for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter “**ASSIGNEE**”), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said **INVENTIONS**, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto **ASSIGNEE**, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said **INVENTIONS**, including all patent applications therefor that may have been filed or may be filed hereafter for said **INVENTIONS** in the United States, including but not limited to U.S. Application No. **16/219,698** filed **December 13, 2018**,

Qualcomm Reference No. **181730**, and all provisional applications relating thereto, together with Indian Application No. **201841003135**, filed **January 26, 2018**, Qualcomm Reference No. **181730IN1**, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
LOCATION DATE
Helena Deirdre O'SHEA

Done at _____, on _____
LOCATION DATE
Lalan Jee MISHRA

Done at Haifa, Israel, on 28-Mar-2019
LOCATION DATE

Amit GIL

Done at _____, on _____
LOCATION DATE
Gary CHANG

Done at _____, on _____
LOCATION DATE
Mohit Kishore PRASAD

Done at _____, on _____
LOCATION DATE
Richard Dominic WIETFELDT

Done at _____, on _____
LOCATION DATE
Vinay JAIN

ASSIGNMENT

WHEREAS, WE,

1. **Helena Deirdre O'SHEA**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
2. **Lalan Jee MISHRA**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
3. **Amit GIL**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
4. **Gary CHANG**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
5. **Mohit Kishore PRASAD**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
6. **Richard Dominic WIETFELDT**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
7. **Vinay JAIN**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **EFFICIENT TECHNIQUE FOR COMMUNICATING BETWEEN DEVICES OVER A MULTI-DROP BUS** (collectively the “**INVENTIONS**”) for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter “**ASSIGNEE**”), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said **INVENTIONS**, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto **ASSIGNEE**, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said **INVENTIONS**, including all patent applications therefor that may have been filed or may be filed hereafter for said **INVENTIONS** in the United States, including but not limited to U.S. Application No. **16/219,698** filed **December 13, 2018**,

Qualcomm Reference No. **181730**, and all provisional applications relating thereto, together with Indian Application No. **201841003135**, filed **January 26, 2018**, Qualcomm Reference No. **181730IN1**, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
LOCATION DATE

Helena Deirdre O'SHEA

Done at _____, on _____
LOCATION DATE

Lalan Jee MISHRA

Done at _____, on _____
LOCATION DATE

Amit GIL

Done at Santa Clara, on 3/27/19
LOCATION DATE


Gary CHANG

Done at _____, on _____
LOCATION DATE

Mohit Kishore PRASAD

Done at _____, on _____
LOCATION DATE

Richard Dominic WIETFELDT

Done at _____, on _____
LOCATION DATE

Vinay JAIN

ASSIGNMENT

WHEREAS, WE,

1. **Helena Deirdre O'SHEA**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
2. **Lalan Jee MISHRA**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
3. **Amit GIL**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
4. **Gary CHANG**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
5. **Mohit Kishore PRASAD**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
6. **Richard Dominic WIETFELDT**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
7. **Vinay JAIN**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **EFFICIENT TECHNIQUE FOR COMMUNICATING BETWEEN DEVICES OVER A MULTI-DROP BUS** (collectively the “**INVENTIONS**”) for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter “**ASSIGNEE**”), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said **INVENTIONS**, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto **ASSIGNEE**, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said **INVENTIONS**, including all patent applications therefor that may have been filed or may be filed hereafter for said **INVENTIONS** in the United States, including but not limited to U.S. Application No. **16/219,698** filed **December 13, 2018**,

Qualcomm Reference No. **181730**, and all provisional applications relating thereto, together with Indian Application No. **201841003135**, filed **January 26, 2018**, Qualcomm Reference No. **181730IN1**, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

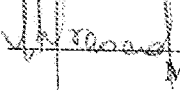
AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
LOCATION DATE
_____ Helena Deirdre O'SHEA

Done at _____, on _____
LOCATION DATE
_____ Lalan Jee MISHRA

Done at _____, on _____
LOCATION DATE
_____ Amit GIL

Done at _____, on _____
LOCATION DATE
_____ Gary CHANG

Done at SAN DIEGO, CA, on 4/5/19
LOCATION DATE
 _____ Mohit Kishore PRASAD

Done at _____, on _____
LOCATION DATE
_____ Richard Dominic WIETFELDT

Done at _____, on _____
LOCATION DATE
_____ Vinay JAIN

ASSIGNMENT

WHEREAS, WE,

1. **Helena Deirdre O'SHEA**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
2. **Lalan Jee MISHRA**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
3. **Amit GIL**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
4. **Gary CHANG**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
5. **Mohit Kishore PRASAD**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
6. **Richard Dominic WIETFELDT**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,
7. **Vinay JAIN**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121-1714**,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **EFFICIENT TECHNIQUE FOR COMMUNICATING BETWEEN DEVICES OVER A MULTI-DROP BUS** (collectively the “**INVENTIONS**”) for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter “**ASSIGNEE**”), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said **INVENTIONS**, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto **ASSIGNEE**, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said **INVENTIONS**, including all patent applications therefor that may have been filed or may be filed hereafter for said **INVENTIONS** in the United States, including but not limited to U.S. Application No. **16/219,698** filed **December 13, 2018**,

Qualcomm Reference No. **181730**, and all provisional applications relating thereto, together with Indian Application No. **201841003135**, filed **January 26, 2018**, Qualcomm Reference No. **181730IN1**, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
LOCATION DATE Helena Deirdre O'SHEA

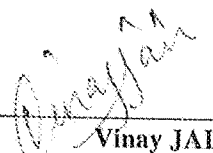
Done at _____, on _____
LOCATION DATE Lalun Jee MISHRA

Done at _____, on _____
LOCATION DATE Amit GIL

Done at _____, on _____
LOCATION DATE Gary CHANG

Done at _____, on _____
LOCATION DATE Mohit Kishore PRASAD

Done at _____, on _____
LOCATION DATE Richard Dominic WIETFELODT

Done at Bengaluru, India, on April 3rd, 2019
LOCATION DATE  Vinay JAIN